

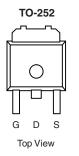
N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A) ^a		
60	0.026 at V _{GS} = 10 V	45		
	0.029 at V _{GS} = 4.5 V	40		

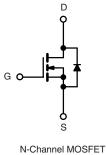
FEATURES

- TrenchFET[®] Power MOSFET
- 175 °C Junction Temperature





Drain Connected to Tab



ABSOLUTE MAXIMUM RATINGS $T_C = 2$	25 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C	1-	40		
Continuous Drain Current $(T_J = 175 \ ^{\circ}C)^{b}$	T _C = 100 °C	- I _D	35		
Pulsed Drain Current		I _{DM}	100	A	
Continuous Source Current (Diode Conduction)		۱ _S	23		
Avalanche Current		I _{AS}	20		
Single Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AS}	20	mJ	
	T _C = 25 °C	D_	100	w	
Maximum Power Dissipation	T _A = 25 °C	• P _D -	3 ^a		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	$t \le 10 \text{ sec}$	- R _{thJA}	18	22	°C/W
Maximum Junction-to-Ambient*	Steady State		40	50	
Maximum Junction-to-Case		R _{thJC}	3.2	4	

Notes:

a. Surface Mounted on 1" x 1" FR4 board, t \leq 10 sec.

SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min	Typ ^a	Мах	Unit	
Static	•						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 250 μ A	60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.0	2.0	3.0	- V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50	μA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 10 V$	50			Α	
		V _{GS} = 10 V, I _D = 15 A		0.026		Ω	
		V_{GS} = 10 V, I _D = 15 A, T _J = 125 °C		0.055			
Drain-Source On-State Resistance ^b	r _{DS(on)}	V _{GS} = 10 V, I _D = 15 A, T _J = 175 °C		0.069			
		V _{GS} = 4.5 V, I _D = 10 A		0.029			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		20		S	
Dynamic ^a	•						
Input Capacitance	C _{iss}			1850		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		140			
Reverse Transfer Capacitance	C _{rss}			60			
Total Gate Charge ^c	Qg			11	17	nC	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 23 A		3			
Gate-Drain Charge ^c	Q _{gd}			3			
Turn-On Delay Time ^c	t _{d(on)}			8	15		
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } \text{R}_{\text{L}} = 1.3 \ \Omega$ $\text{I}_{\text{D}} \cong 23 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V, } \text{R}_{\text{g}} = 2.5 \ \Omega$		15	25	ns	
Turn-Off Delay Time ^c	t _{d(off)}			30	45		
Fall Time ^c	t _f			25	40		
Source-Drain Diode Ratings and Cha	aracteristics	(T _C = 25 °C)			I		
Pulsed Current	I _{SM}				50	А	
Diode Forward Voltage	V _{SD}	I _F = 15 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 15 A, di/dt = 100 A/μs		30	60	ns	

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

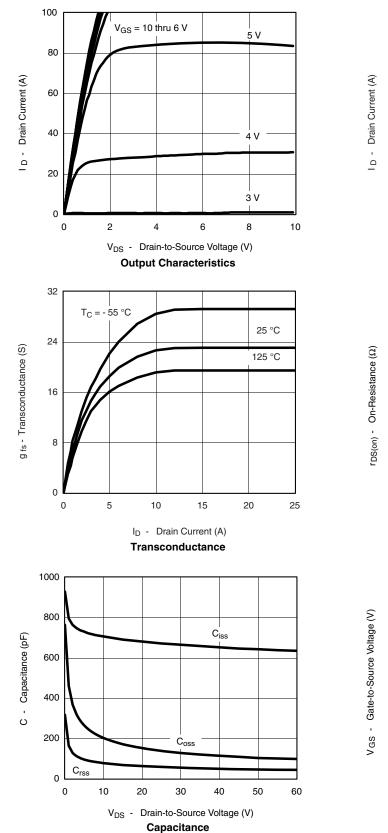
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

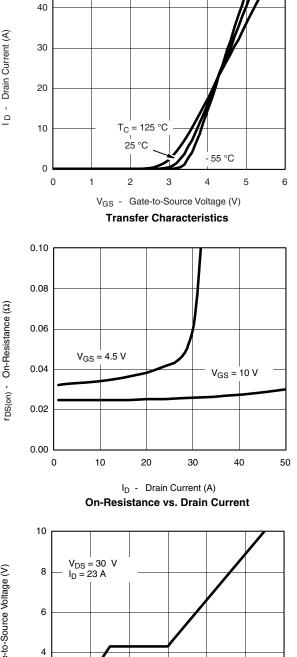
emi

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TYPICAL CHARACTERISTICS 25 °C unless noted



Qg - Total Gate Charge (nC)

Gate Charge



 $T_J = 25 \degree C$

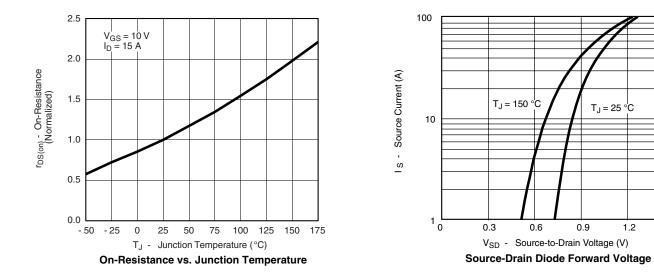
1.2

1.5

 $T_{J} = 150 °^{I}C$

0.6

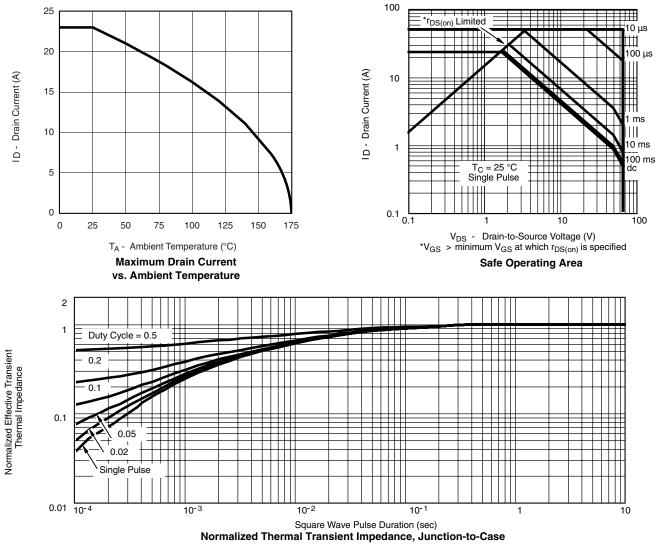
0.9



TYPICAL CHARACTERISTICS 25 °C unless noted



THERMAL RATINGS





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